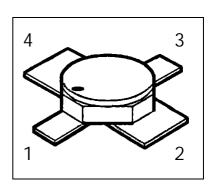


HiRel NPN Silicon RF Transistor

- HiRel Discrete and Microwave Semiconductor
- For low noise, high-gain amplifiers up to 2GHz.
- For linear broadband amplifiers
- Hermetically sealed microwave package
- f_T= 6,5 GHz
 F = 3 dB at 2 GHz

ESA/SCC Detail Spec. No.: 5611/006 Type Variant No. 07 (tbc.)

Type variant No. 07 (tbc.)



ESD: Electrostatic discharge sensitive device, observe handling precautions!

Туре	Marking	Ordering Code	Pin Configuration		Package		
BFY196 (ql)	-	see below	С	E	В	E	Micro-X1

(ql) Quality Level: P: Professional Quality, Ordering Code: Q62702F1684

H: High Rel Quality,S: Space Quality,Ordering Code: on requeston request

(see order instructions for ordering example)



Maximum	Ratings

Parameter	Symbol	Values	Unit	
Collector-emitter voltage	V_{CEO}	12	V	
Collector-emitter voltage, V _{BE} =0	V _{CES}	20	V	
Collector-base voltage	V_{CBO}	20	V	
Emitter-base voltage	V _{EBO}	2	V	
Collector current	I _C	100	mA	
Base current	I _B	12 ¹⁾	mA	
Total power dissipation, $T_S \le 105^{\circ}C^{2), 3)}$	P _{tot}	700	mW	
Junction temperature	T _j	200	°C	
Operating temperature range	T _{op}	-65+200	°C	
Storage temperature range	T _{stg}	-65+200	°C	
Thermal Resistance		•		
Junction-soldering point 3.)	R _{th JS}	< 135	K/W	

Notes.:

Electrical Characteristics

at $T_A=25$ °C; unless otherwise specified

Parameter	Symbol	Values		Unit		
		min.	typ.	max.		
DC Characteristics						
Collector-base cutoff current	I _{CBO}	-	-	100	μΑ	
$V_{CB} = 20 \text{ V}, I_{E} = 0$						
Collector-emitter cutoff current	I _{CEX}	-	-	1000	μΑ	
$V_{CE} = 12 \text{ V}, I_{B} = 1 \mu A^{-1.}$						
Collector-base cutoff current	I _{CBO}	-	-	50	nA	
$V_{CB} = 10 \text{ V}, I_{E} = 0$						
Emitter base cuttoff current	I _{EBO}	-	-	25	μΑ	
$V_{EB} = 2 \text{ V}, I_{C} = 0$						
Emitter base cuttoff current	I _{EBO}	-	-	0.5	μΑ	
$V_{EB} = 1 \text{ V}, I_{C} = 0$						

Notes:

1.) This Test assures V(BR)CE0 > 12V

¹⁾ The maximum permissible base current for V_{FBE} measurements is 50mA (spot-measurement duration < 1s)

²⁾ At T_S = + 105 °C. For T_S > + 105 °C derating is required.

³⁾ T_s is measured on the collector lead at the soldering point to the pcb.



Electrical Characteristics (continued)

Parameter	Symbol	ol Values			Unit	
		min.	typ.	max.		
DC Characteristics	<u> </u>			•		
Base-Emitter forward voltage	V_{FBE}	-	-	1	V	
$I_E = 50 \text{ mA}, I_C = 0$						
DC current gain	h _{FE}	50	100	175	-	
$I_{C} = 50 \text{ mA}, V_{CE} = 8 \text{ V}$						
AC Characteristics						
Transition frequency	f _T	6	6.5	-	GHz	
I_C = 70 mA, V_{CE} = 5 V, f = 500 MHz						
Collector-base capacitance	ССВ	-	1	1.3	pF	
$V_{CB} = 10 \text{ V}, V_{BE} = \text{vbe} = 0, f = 1 \text{ MHz}$						
Collector-emitter capacitance	C _{CE}	-	0.44	-	pF	
V_{CE} = 10 V, V_{BE} = vbe = 0, f = 1 MHz						
Emitter-base capacitance	C _{EB}	-	3,6	4,3	pF	
$V_{EB} = 0.5V$, $V_{CB} = vcb = 0$, $f = 1 MHz$						
Noise Figure	F	-	3	3.5	dB	
$I_C = 20 \text{ mA}, V_{CE} = 5 \text{ V}, f = 2 \text{ GHz},$						
$Z_S = Z_{Sopt}$						
Power gain	Gma 1.)	10	11	-	dB	
$I_C = 70 \text{ mA}$, $V_{CE} = 5V$, $f = 2 \text{ GHz}$						
$Z_S = Z_{Sopt}$, $Z_L = Z_{Lopt}$						
Transducer gain	$\left S_{21e}\right ^2$	4	5	-	dB	
$I_C = 70 \text{ mA}$, $V_{CE} = 5 \text{ V}$, $f = 2 \text{ GHz}$						
$Z_S = Z_L = 50 \Omega$						
Output Power	P _{OUT}	18.5	19.5	-	dBm	
I_C = 80 mA, V_{CE} = 5 V, f = 2 GHz ,						
P_{IN} =15 dBm, $Z_S = Z_L = 50 \Omega$						

Notes.:

1)
$$G_{ma} = \left| \frac{S21}{S12} \right| (k - \sqrt{k^2 - 1}), \quad G_{ms} = \left| \frac{S21}{S12} \right|$$



Order Instructions:

Full type variant including quality level must be specified by the orderer. For *HiRel* Discrete and Microwave Semiconductors the ordering code specifies device family and quality level.

Ordering Form:

Ordering Code: Q.....

BFY196 (ql)

(ql): Quality Level

Ordering Example:

Ordering Code: Q62702F1684

BFY196 P

For BFY196 in Professional Quality Level

Further Informations:

See our WWW-Pages:

- Discrete and RF-Semiconductors (Small Signal Semiconductors) www.infineon.com/product/discrete/hirel.htm

 HiRel Discrete and Microwave Semiconductors www.infineon.com/product/discrete/hirel.htm

Please contact also our marketing division :

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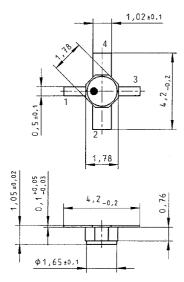
Address: Infineon Technologies Semiconductors,

High Frequency Products Marketing,

P.O.Box 801709, D-81617 Munich



Micro-X1 Package



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